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## Product Change Notification - JAON-14YQYH505

**Date:** 07 Nov 2016  
**Product Category:** Memory  
**Notification subject:** CCB 2700 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 160K wafer technology available in 8L SOIC package at MMT assembly site.  
**Notification text:** **PCN Status:**  
Final notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 160K wafer technology available in 8L SOIC package at MMT assembly site.

**Pre Change:**

Using gold (Au) bond wire

**Post Change:**

Using palladium coated copper with gold flash (CuPdAu) bond wire

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	MMT assembly site	MMT assembly site
<b>Wire material</b>	Au wire	CuPdAu wire
<b>Die attach material</b>	8390A	8390A
<b>Molding compound material</b>	G600V	G600V
<b>Lead frame material</b>	CDA194	CDA194

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve manufacturability and qualify palladium coated copper with gold flash (CuPdAu) bond wire

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**  
December 2, 2016 (date code: 1648)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	July 2016				->	November 2016				December 2016				
	27	28	29	30		44	45	46	47	48	49	50	51	52
Initial PCN Issue Date			X											
Qual Report Availability						X								
Final PCN Issue Date						X								
Estimated Implementation Date										X				

**Method to Identify Change:**  
Traceability code

**Qualification Report:**  
Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

**Revision History:**  
**July 19, 2016:** Issued initial notification.  
**November 7, 2016:** Issued final notification. Attached the qualification report. Provided estimated first ship date on December 2, 2016.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):** [PCN\\_JAON-14YQYH505\\_Qual\\_Report.pdf](#)  
[PCN\\_JAON-14YQYH505\\_Affected\\_CPN.pdf](#)  
[PCN\\_JAON-14YQYH505\\_Affected\\_CPN.xlsx](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-14YQYH505
CATALOG_PART_NBR
24AA01/SN
24AA01-I/SN
24AA01T/SN
24AA01T-I/SN
24AA02/SN
24AA024H-I/SN
24AA024HT-I/SN
24AA024-I/SN
24AA024T-I/SN
24AA025E48-E/SN
24AA025E48-I/SN
24AA025E48T-E/SN
24AA025E48T-I/SN
24AA025E64-E/SN
24AA025E64-I/SN
24AA025E64T-E/SN
24AA025E64T-I/SN
24AA025-I/SN
24AA025T-I/SN
24AA025UID-I/SN
24AA025UIDT-I/SN
24AA02E48-E/SN
24AA02E48-I/SN
24AA02E48T-E/SN
24AA02E48T-I/SN
24AA02E64-E/SN
24AA02E64-I/SN
24AA02E64T-E/SN
24AA02E64T-I/SN
24AA02H-I/SN
24AA02HT-I/SN
24AA02-I/SN
24AA02T/SN
24AA02T-I/SN
24AA02UID-I/SN
24AA02UIDT-I/SN
24LC01B/SN
24LC01B-E/SN
24LC01B-I/SN
24LC01BT/SN
24LC01BT-E/SN
24LC01BT-I/SN
24LC024/SN

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Affected Catalog Part Numbers (CPN)

PCN_JAON-14YQYH505
CATALOG_PART_NBR
24LC024-E/SN
24LC024H-E/SN
24LC024H-I/SN
24LC024HT-E/SN
24LC024HT-I/SN
24LC024-I/SN
24LC024T/SN
24LC024T-E/SN
24LC024T-I/SN
24LC025/SN
24LC025-E/SN
24LC025-I/SN
24LC025T/SN
24LC025T-E/SN
24LC025T-I/SN
24LC02B/SN
24LC02B-E/SN
24LC02BH-E/SN
24LC02BH-I/SN
24LC02BH-I/SN100
24LC02BHT-E/SN
24LC02BHT-I/SN
24LC02B-I/SN
24LC02B-I/SNA32
24LC02BT/SN
24LC02BT/SNA31
24LC02BT-E/SN
24LC02BT-I/SN
24LC02BT-I/SN104
24LC02BT-I/SNA32
24VL024/SN
24VL024H/SN
24VL024HT/SN
24VL024T/SN
24VL025/SN
24VL025T/SN